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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
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10/761,223

01/22/2004

Hiroyuki Fukunaga

OKI.616

2739

20987

7590

10/05/2006

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EXAMINER

KEBEDE, BROOK

ART UNIT

PAPER NUMBER

2823

DATE MAILED: 10/05/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

<b>Office Action Summary</b>	<b>Application No.</b>	<b>Applicant(s)</b>	
	10/761,223	FUKUNAGA, HIROYUKI	
	<b>Examiner</b>	<b>Art Unit</b>	
	Brook Kebede	2823	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --  
**Period for Reply**

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

#### Status

- 1) ☒ Responsive to communication(s) filed on 30 September 2006.
- 2a) ☐ This action is **FINAL**.                      2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

#### Disposition of Claims

- 4) ☒ Claim(s) 1,6,9,10 and 14 is/are pending in the application.
- 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 1,6,9,10 and 14 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

#### Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on \_\_\_\_\_ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

#### Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All    b) ☐ Some \*    c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
  2. ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
  3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

#### Attachment(s)

- |  |   |
|--|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892)  | 4) <input type="checkbox"/> Interview Summary (PTO-413)<br>Paper No(s)/Mail Date. _____ |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)                                   | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152)             |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)<br>Paper No(s)/Mail Date _____ | 6) <input type="checkbox"/> Other: _____  |

## **DETAILED ACTION**

### ***Continued Examination Under 37 CFR 1.114***

1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on September 12, 2006 has been entered.

### ***Claim Rejections - 35 USC § 103***

2. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

3. Claims 1, 6, 9, 10 and 14 are rejected under 35 U.S.C. 103(a) as being unpatentable over Chiu et al. (US/4,514,897) in view of Gardner et al. (US/5,888,870).

Re claim 1, Chiu et al. disclose A method of manufacturing a nonvolatile semiconductor storage device, comprising: the first step of successively forming a first insulating film (23) and a first polysilicon layer (13) on a semiconductor substrate (20); patterning the first polysilicon layer (13) and the first insulating (23) film into the shape of a band; thermally oxidizing the patterned band-shaped first polysilicon layer (13), thereby to form a second insulating film (24) which is thicker at side surfaces of the first polysilicon layer (13) than at the front surface thereof; forming a second polysilicon layer (14) on a front surface of the resulting semiconductor substrate formed with the second insulating film (24); performing patterning so as to form each

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storage element of the nonvolatile semiconductor storage device as includes the first insulating film (23) , a floating gate electrode made of the first polysilicon layer (13), the second insulating film (24), and a control gate electrode made of the second polysilicon layer (14) (see Figs. 2, 5a-5f, and 7 and related text in Col. 2, line 40 – Col. 8, line 15).

However, Chiu et al. do not specifically disclose implanting nitrogen ions into a front surface of the first polysilicon layer.

Gardner et al. disclose a method of fabricating nonvolatile memory device the method includes forming the first polysilicon layer (36) on the first insulating layer (34) (see Fig. 3) and implanting of the first polysilicon layer (36) with nitrogen ion (see Fig. 4) wherein the nitrogen ions into the first polysilicon layer (36) so as to be located only in the front surface of the first polysilicon layer (36) (see Fig. 5) in order to block migration of foreign species into the floating gate (i.e., the first polysilicon layer) (see Gardner et al. Figs. 3-5 and related text in Col. 6, lines 28-52).

Therefore, it would have been obvious to one having ordinary skill in the art at the time of applicant(s) claimed invention was made to provide Chiu et al. reference with implanting nitrogen ions into a front surface of the first polysilicon layer as taught by Gardner et al. in order to block migration of foreign species into the floating gate (i.e., the first polysilicon layer).

Re claim 6, as applied to claim 1 above, Chiu et al. and Gardner et al. in combination disclose all the claimed limitations including wherein the first polysilicon layer has a thickness of 20 – 40 nm (i.e., within the overlap claimed range of 20 to 50 nm) implanting nitrogen ions with predetermined energy and ion concentration. Furthermore, the claimed nitrogen dopant energy

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level and ion concentration can be achieved by routine optimization in order to achieve the desired device performance.

Therefore, it would have been to one having ordinary skill in the art at the time of the invention is made to the dopant energy and concentration level, since it has been held where the general conditions of a claim are disclosed in the prior art, it is not inventive to discover the optimum or workable ranges by routine experimentation.” See *In re Aller*, 220 F.2d 454, 456, 105 USPQ 233, 235 (CCPA 1955); *In re Hoeschele*, 406 F.2d 1403, 160 USPQ 809 (CCPA 1969); *Merck & Co. Inc. v. Biocraft Laboratories Inc.*, 874 F.2d 804, 10 USPQ2d 1843 (Fed. Cir.), cert. denied, 493 U.S. 975 (1989); *In re Kulling*, 897 F.2d 1147, 14 USPQ2d 1056 (Fed. Cir. 1990); and *In re Geisler*, 116 F.3d 1465, 43 USPQ2d 1362 (Fed. Cir. 1997). Furthermore, the specification contains no disclosure of either the critical nature of the claimed acceleration voltage as well as dopant concentration or any unexpected results arising therefrom. Where patentability is said to be based upon particular chosen dimensions or upon another variable recited in a claim, the Applicant must show that the chosen dimensions are critical. See *In re Woodruff*, 919 F.2d 1575, 1578, 16 USPQ2d 1936 (Fed. Cir. 1990).

Re claims 9 and 10, Chiu et al. disclose a method of manufacturing a nonvolatile semiconductor storage device, comprising: the first step of successively forming a first insulating film (23) and a first polysilicon layer (13) on a semiconductor substrate (20); patterning the first polysilicon layer (13) and the first insulating (23) film into the shape of a band; thermally oxidizing the patterned band-shaped first polysilicon layer (13), thereby to form a second insulating film (24) which is thicker at side surfaces of the first polysilicon layer (13) than at the front surface thereof; forming a second polysilicon layer (14) on a front surface of the resulting

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semiconductor substrate formed with the second insulating film (24); performing patterning so as to form each storage element of the nonvolatile semiconductor storage device as includes the first insulating film (23), a floating gate electrode made of the first polysilicon layer (13), the second insulating film (24), and a control gate electrode made of the second polysilicon layer (14) (see Figs. 2, 5a-5f, and 7 and related text in Col. 2, line 40 – Col. 8, line 15).

However, Chiu et al. do not specifically disclose implanting nitrogen ions into a front surface of the first polysilicon layer.

Gardner et al. disclose a method of fabricating nonvolatile memory device the method includes forming the first polysilicon layer (36) on the first insulating layer (34) (see Fig. 3) and implanting of the first polysilicon layer (36) with nitrogen ion (see Fig. 4) wherein said implanting nitrogen ions (see Fig. 4) is performed prior to said patterning the first insulating film (34) and the first polysilicon layer (36), and wherein the nitrogen ions are implanted into the first polysilicon layer (36) so as to be located only in the front surface of the first polysilicon layer (see Fig. 5) in order to block migration of foreign species into the floating gate (i.e., the first polysilicon layer) (see Gardner et al. Figs. 3-5 and related text in Col. 6, lines 28-52).

Therefore, it would have been obvious to one having ordinary skill in the art at the time of applicant(s) claimed invention was made to provide Chiu et al. reference with implanting nitrogen ions into a front surface of the first polysilicon layer as taught by Gardner et al. in order to block migration of foreign species into the floating gate (i.e., the first polysilicon layer).

Re claim 14, as applied to claim 9 above, Chiu et al. and Gardner et al. in combination disclose all the claimed limitations including wherein the first polysilicon layer has a thickness of 20 – 40 nm (i.e., within the overlap claimed range of 20 to 50 nm) implanting nitrogen ions with

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predetermined energy and ion concentration. Furthermore, the claimed nitrogen dopant energy level and ion concentration can be achieved by routine optimization in order to achieve the desired device performance.

Therefore, it would have been to one having ordinary skill in the art at the time of the invention is made to the dopant energy and concentration level, since it has been held where the general conditions of a claim are disclosed in the prior art, it is not inventive to discover the optimum or workable ranges by routine experimentation.” See *In re Aller*, 220 F.2d 454, 456, 105 USPQ 233, 235 (CCPA 1955); *In re Hoeschele*, 406 F.2d 1403, 160 USPQ 809 (CCPA 1969); *Merck & Co. Inc. v. Biocraft Laboratories Inc.*, 874 F.2d 804, 10 USPQ2d 1843 (Fed. Cir.), cert. denied, 493 U.S. 975 (1989); *In re Kulling*, 897 F.2d 1147, 14 USPQ2d 1056 (Fed. Cir. 1990); and *In re Geisler*, 116 F.3d 1465, 43 USPQ2d 1362 (Fed. Cir. 1997). Furthermore, the specification contains no disclosure of either the critical nature of the claimed acceleration voltage as well as dopant concentration or any unexpected results arising therefrom. Where patentability is said to be based upon particular chosen dimensions or upon another variable recited in a claim, the Applicant must show that the chosen dimensions are critical. See *In re Woodruff*, 919 F.2d 1575, 1578, 16 USPQ2d 1936 (Fed. Cir. 1990).

#### ***Response to Arguments***

4. Applicants’ arguments with respect to claims 1, 6, 9, 10 and 14 have been considered but are moot in view of the new ground(s) of rejection that was necessitated by the amendment filed on August 15, 2005.

#### ***Conclusion***

5. **THIS ACTION IS MADE NON-FINAL.**


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*Correspondence*

6. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Brook Kebede whose telephone number is (571) 272-1862. The examiner can normally be reached on 8-5 Monday to Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Matthew S. Smith can be reached on (571) 272-1907. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

  
Brook Kebede  
Primary Examiner  
Art Unit 2823

BK  
September 30, 2006